

C1210X333G2TACTU

Aliases (C1210X333G2TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 0.033 uF, 2%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	52 mg	
Shelf Life	78 Weeks	
MSL	1	

0.033 uF

Time is 1000 Hours

30.303 GOhms

Dimensions	
Chip Size	1210
L	3.3mm +/-0.4mm
W	2.6mm +/-0.3mm
Т	1.55mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

	3.3mm +/-0.4mm	Measurement Condition	1 kHz 1.0Vrms
	2.6mm +/-0.3mm	Tolerance	2%
	1.55mm +/-0.20mm	Voltage DC	200 VDC
	1.5mm MIN	Dielectric Withstanding Voltage	500 VDC
	0.6mm +/-0.25mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
ns	T&R, 180mm, Plastic Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
	2000	Dissipation Factor	0.1% 1 kHz 1.0Vrms
		Aging Rate	0% Loss/Decade Hour: Referee

Insulation Resistance

Specifications

Capacitance

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2000

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